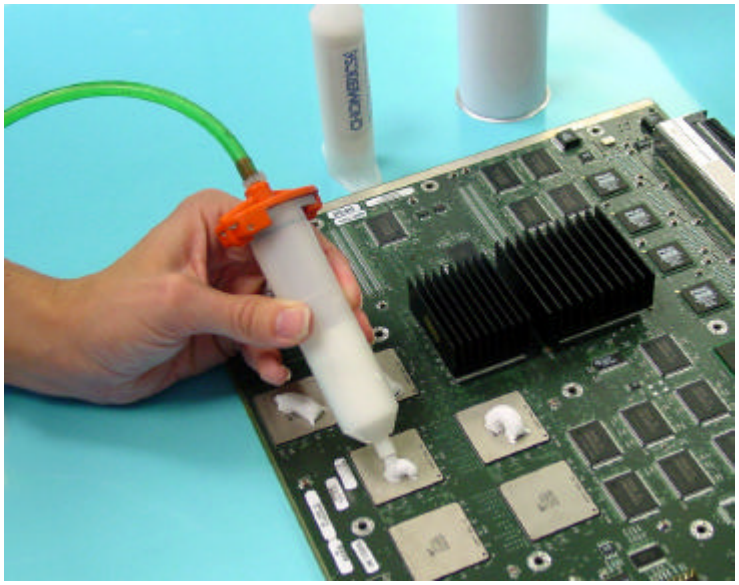
THERM-A-GAP™ T630
Thermally Conductive Form-in-Place Gap Filler

DESCRIPTION

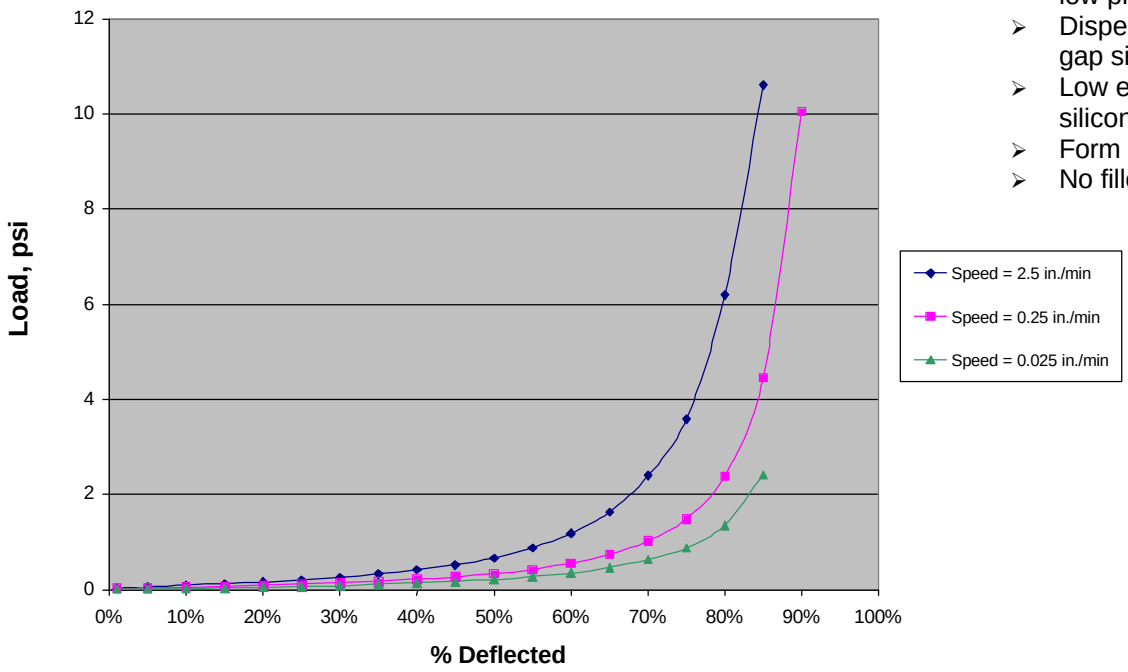
THERM-A-GAP T630 is Chomerics' latest development in thermally conductive gap fillers. This unique material is ideal for applications where typical gap filling pads cause too much stress on component solder joints and leads, resulting in damage to the printed circuit board. T630 is a highly conformable, one component pre-cured silicone that can be dispensed to fill large and uneven gaps in electronics assemblies. This viscoelastic paste is a form stable, fully cured silicone material that takes little to no compressive force to deform during assembly. THERM-A-GAP T630G contains 0.010" glass beads, used for a compression stop for applications requiring electrical isolation. Both products have low extractable silicone levels and pass the Bellcore silicone extractable specification for the telecom industry.



FEATURES

- Requires no curing
- Highly conformable at low pressures
- Dispensable for any gap size > 0.010"
- Low extractable silicone levels
- Form stable
- No filler settling issues

T630 Compression Deflection Characteristics at Low, Medium and High Compression (Strain) Rates



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APPLICATION

T630 and T630G are supplied in 30cc and 300cc aluminum cartridges. Apply pressure to the back of the cartridge, dispense the desired amount onto the component, and swipe the tip along the component to break the bead of material. Excess material can be wiped up with a rag. Refer to our Applications Note for more detailed information about using this material.

HANDLING

To use, simply dispense the gap filling material onto the component, assemble and secure the heat sink or chassis in place, and ship your product. No mixing or cure cycles are required. The ease of application of this material is also ideal for rework and field repair situations. T630 requires no refrigeration, stores at room temperature and has no filler settling issues.

Typical Properties	T630	T630G	Test Method
Color	White	White	Visual
Composition	Ceramic Filled Silicone	Ceramic Filled Silicone with 0.010" (0.25mm) glass beads	- -
Thermal Conductivity, W/m-K	0.7	0.7	ASTM D5470 (modified)
Operating Temperature Range, °C	-50 to 150	-50 to 150	- -
Compression/ Deflection Characteristics 50% Deflection	1 psi	1 psi	ASTM C165 (modified)
Specific Gravity	2.25	2.25	ASTM D792
TGA Weight Loss, 24 hours, 150°C	0.2%	0.2%	ASTM D6375 (modified)
Flammability Rating	V0	V0	UL94, File E140244
Flow Rate*	10cc/min	10cc/min	- -
Extractable Silicones	6%	6%	Telcordia GR78-CORE
Dielectric Strength, Vac/mil @ 10mil	1000	1000	ASTM D149
Volume Resistivity, ohm-cm	1×10^{14}	1×10^{14}	ASTM D257
Shelf Life @ Room Temp.	18 mos.	18 mos.	- -

*30cc taper tip syringe, 0.130 inch orifice at 90 psi.

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